Wafer Dicing Process

Best Platform for Thick, Hard and Brittle Materials

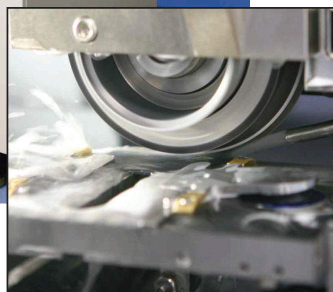
Proven solution for:

> Silicon Carbide (SiC)
> Gallium Arsenide (GaAs)
> Glass Substrates
> Ceramic Substrates

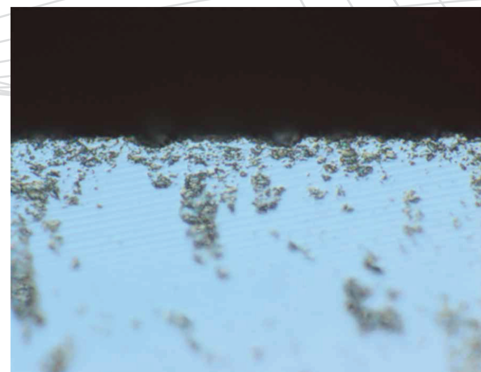
Industry best in:

> **Quality:** minimal chipping
> **Speed:** fastest cycle time
> **Cost:** lowest blade consumption

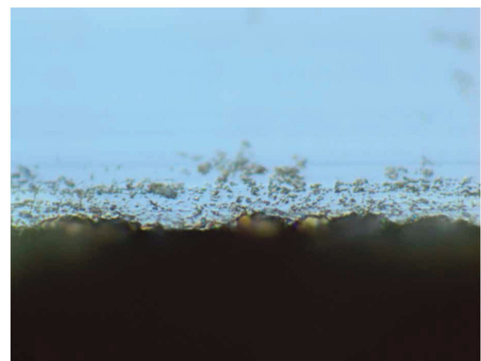
Veeco ADS800™
Advanced Dicing System



Typical SiC Die Edge Quality
on the ADS800 System



Front side chipping <5 μm



Back side chipping <10 μm

#1 Dicing Platform for Aluminum Titanium Carbide (AlTiC)
Wafer Substrates for Thin Film Magnetic Heads

veeco.com